IPC ASSOCIATION CONN ELECTRONICS INDU	© Copyright 2005. II	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both This docu	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information			
upplier Inf	formation													
Company name*			Company unique ID			Unique ID Authority				Res	Response Date*			
nsemi											2023-06-08			
Contact Name			Title - Contact			Phone - Contact*				En	Email - Contact*			
Product-Env-S	Stewards		Product Enviro Compliance			NA				Pr	Product-Env-Stewards@onsemi.com			
uthorized Rep	presentative*		Title - Representative			Phone - Representative*			En	Email - Representative*				
Product-Env-S	Stewards		Product Enviro Compliance			NA				Pr	Product-Env-Stewards@onsemi.com			
Req	quester Item Number	Mfr Item Number		Mfr Item Name		Effective I	Date V	Version Manufacturing Site		ite	Weight*	UOM	Unit Type	
		NCP1060)BD100R2G	HV Switcher for Lo	ow Power offline SMPS	2023-06-08		PH1			86.79	mg	Each	
	ring Process Informat		arminal Paga	Alloy	STD-020 MSL Rating	Dook I	Process	Pody Tompore	tura May Tima of	Pault Tam	postura Numb	per of Reflow Cy	alas	
			Terminal Base Alloy J-STD-02 CU Alloy 1		STD-020 MSL Kating		Peak Process Body Tempera 260 C		ture Max Time at			ber of Reflow Cy	cies	
	te 1111 (SII) - aimeaied	C	O Alloy	1		200		JC	30		seconds 3			
omments	num time at week tommenatu	uno durmina aol	domina ia 10. 2	10 seconds										
	num time at peak temperatu													
r more infori	mation regarding material	composition j	piease reter to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shave provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier is liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.59	mg	Supplier	Silicon (Si)	7440-21-3		2.59	mg
Die Attach	0.45	mg		Epoxy resin	proprietary data		0.09	mg
			Supplier	Silver (Ag)	7440-22-4		0.36	mg
Lead Frame	35.1		Supplier	Silver (Ag)	7440-22-4		0.351	mg
			Supplier	Tin (Sn)	7440-31-5		0.0877	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0772	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0877	mg
			Supplier	Copper (Cu)	7440-50-8		34.4963	mg
Mold Compound-Black	47.0			Epoxy resin	proprietary data		2.35	mg
			Supplier	Phenolic Resin	Proprietary Data		2.35	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.94	mg
			Supplier	Carbon Black (C)	1333-86-4		0.235	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.125	mg
Plating	1.52	mg	Supplier	Tin (Sn)	7440-31-5		1.52	mg
Wire Bond - Au	0.13	mg	Supplier	Gold (Au)	7440-57-5		0.13	mg